

ABSTRACT

A lead-free solder paste printing method is practiced with use of a metal mask of the invention by placing the metal mask 1 on a circuit board 2 having an electrode 21 formed in a predetermined pattern to join an end portion of a lead member 6, and moving a printing squeegee along the upper surface of the metal mask 1 to thereby print a lead-free solder paste on the surface of the electrode 21 on the circuit board 2. The method produces on the electrode 21 of the circuit board 2 two lead-free solder paste patterns 30a, 30a each circular or elliptical in shape and arranged in a direction in which the lead member 6 is to extend from the electrode.